PATENT ASSIGNMENT

Electronic Version v1.1 Stylesheet Version v1.1

SUBMISSION TYPE:		NEW ASSIGNMENT	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:		ASSIGNMENT	ASSIGNMENT	
CONVEYING PARTY D	ATA			
		Name	Execution Date	
Satoru Araki			10/27/2010	
Diane L. Brown			08/25/2010	
Hiroaki Chihaya			08/27/2010	
Dustin W. Erickson			08/26/2010	
David J. Seagle			08/26/2010	
RECEIVING PARTY DA	TA			
Name:	HITACHI GLOBAL STORAGE TECHNOLOGIES NETHERLANDS B.V.			
Street Address:	Locatellikade 1, Parnassustoren, 1076 AZ			
City:	Amsterdam			
State/Country:	NETHERLANDS			
PROPERTY NUMBERS]	
Property Type		Number		
Application Number: 12916		12916256		
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NAME OF SUBMITTER:		Mimi Corona		
Total Attachments: 3				
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PATENT REEL: 025353 FRAME: 0002

ASSIGNMENT FOR PATENT APPLICATION

Whereas, I/we the undersigned inventor(s) have invented certain improvements as set forth in the patent application entitled:

MATERIAL FOR USE IN A TMR READ GAP WITHOUT ADVERSELY AFFECTING THE TMR EFFECT

Whereas, Hitachi Global Storage Technologies Netherlands B.V., having a place of business at Locatellikade 1, Parnassustoren, 1076 AZ Amsterdam, The Netherlands (hereinafter referred to as "HITACHI"), desires to acquire the entire right, title and interest in the said application and invention, and to any United States and foreign patents to be obtained therefore;

Now therefore, for a valuable consideration, receipt whereof is hereby acknowledged, I/we, the above named, hereby sell, assign, and transfer to HITACHI, its successors and assigns, the entire right, title and interest in the said application and invention therein disclosed for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and we request the Commissioner of Patents to issue any Letters Patent granted upon the inventions set forth in said application to HITACHI, its successors and assigns; and we hereby agree that HITACHI may apply for foreign Letters Patent on said invention and we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by HITACHI.

Signed on the date(s) indicated beside my (our) signature(s).

1) Signature: 2000 Typed Name: Satoru Araki

Date: 10/27/10

- 2) Signature: Typed Name: Diane L. Brown
- Signature: Typed Name: Hiroaki Chihaya
- Signature: Typed Name: Dustin W. Erickson
- 5) Signature: Typed Name: David J. Seagle

Date:	
Date:	
Date:	
Date:	

Hitachi Docket No.: HSJ920100015US2

Page 1 of 1

PATENT REEL: 025353 FRAME: 0003

ASSIGNMENT FOR PATENT APPLICATION

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Signed on the date(s) indicated beside my (our) signature(s).

 Signature: Typed Name: Satoru Araki

Signature: <u>June</u> Z. Typed Name: Diane L. Brown 2)

 Signature: Typed Name: Hiroaki Chihaya

4)

5) Signature:

Date:

Date: 8/25/

Date: _____

Date: <u>2/2/240</u>

Date: _____8/26/10

PATENT Page 1 of 1 REEL: 025353 FRAME: 0004

ASSIGNMENT FOR PATENT APPLICATION

Whereas, I/we the undersigned inventor(s) have invented certain improvements as set forth in the patent application entitled:

MATERIAL FOR USE IN A TMR READ GAP WITHOUT ADVERSELY AFFECTING THE TMR EFFECT

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Signed on the date(s) indicated beside my (our) signature(s).

1) Signature: Typed Name: Satoru Araki

2) Signature: Typed Name: Diane L. Brown

Signature: Hiroaki Chihaya Typed Name: Hiroaki Chihaya

3)

- 4) Signature: Typed Name: Dustin W. Erickson
- 5) Signature: Typed Name: David J. Seagle

Hitachi Docket No.: HSJ920100015US2

Date:

Date:

Date: Aug. 27. 2010

Date:

Date:

Page 1 of 1

PATENT REEL: 025353 FRAME: 0005

RECORDED: 11/11/2010